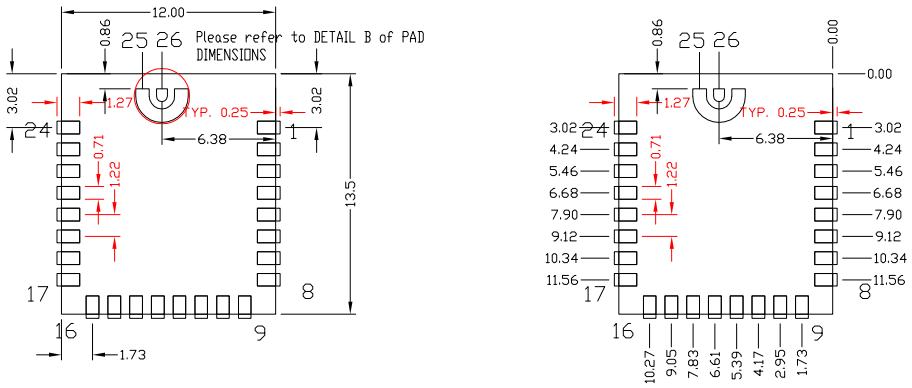
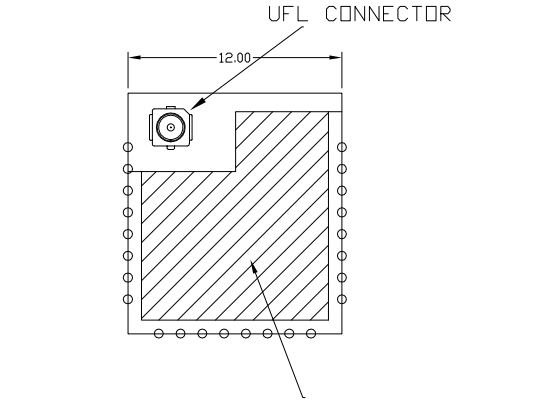
REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
0.1_1	INITIAL RELEASE	WW1837	

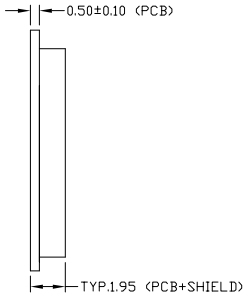
RECOMMEND PCB PATTERN

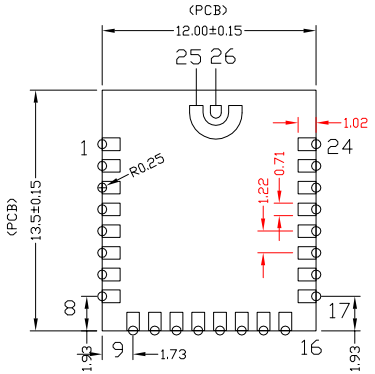


MODULE PAD ASSIGNMENT:

PAD1:P0/P34
PAD2:I2C_SCL
PAD3:XRES
PAD4:I2C_SDA
PAD5:P2/P37/P28
PAD6:SPI2_CS_N
PAD7:GND
PAD8:SPI2_MISO
PAD9:SPI2_MOSI
PAD10:SPI2_CLK
PAD11:GPIO_0
PAD12:GPIO_1
PAD13:GND
PAD14:GPIO_4
PAD15:P4/P24
PAD16:UART_TXD
PAD17:UART_CTS
PAD18:UART_RTS
PAD19:GPIO_7
PAD20:UART_RXD
PAD21:VDDIN
PAD22:GPIO_3
PAD23:GPIO_6
PAD24:GND
PAD25:GND-for 333032 only
PAD26:ANT-for 333032 only







SEEN FROM TOP **SEEN FROM SIDE** **SEEN FROM BOTTOM**



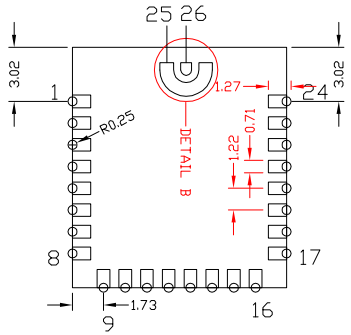
SCALE 1:1

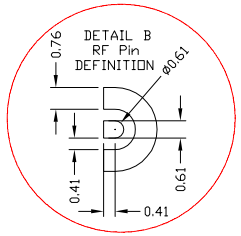
UNLESS OTHERWISE SPECIFIED	SIGNATURES	DATE	CYPRESS SEMICONDUCTOR Corp.
DIMENSIONS ARE IN MM TOLERANCES ON: +/- 0.15 MM ANGLES +/-0.5 DEGREE	DRAWN:	WW1837	CYBT-333032/333047-02
	CHECKED		
	ENGRG		
	ISSUED		

SIZE	REV NO	DWG NO
	0.1_1	

SCALE 5:1 | THE 3RD PROJECTION | SHEET: 1 OF 1

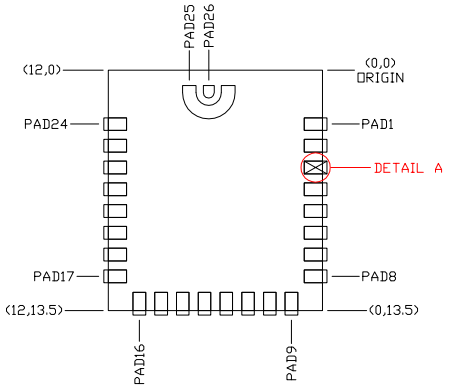
PAD DIMENSIONS

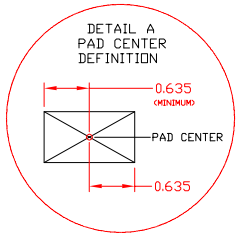




SOLDER PAD AND LOCATION

Solder Pad (Center of Pad)	Location (X,Y) from Orign (mm)	Dimension from Orign (mil)
1	(0.38, 3.02)	(14.96, 118.90)
2	(0.38, 4.24)	(14.96, 166.93)
3	(0.38, 5.46)	(14.96, 214.96)
4	(0.38, 6.68)	(14.96, 262.99)
5	(0.38, 7.90)	(14.96, 311.02)
6	(0.38, 9.12)	(14.96, 359.05)
7	(0.38, 10.34)	(14.96, 407.09)
8	(0.38, 11.56)	(14.96, 455.12)
9	(1.73,13.09)	(68.11, 515.35)
10	(2.95,13.09)	(116.14, 515.35)
11	(4.17,13.09)	(164.17, 515.35)
12	(5.39,13.09)	(212.20, 515.35)
13	(6.61,13.09)	(260.24, 515.35)
14	(7.83,13.09)	(308.27, 515.35)
15	(9.05,13.09)	(356.30, 515.35)
16	(10.27,13.09)	(404.33, 515.35)
17	(11.62,11.56)	(457.48, 455.12)
18	(11.62,10.34)	(457.48, 407.09)
19	(11.62,9.12)	(457.48, 359.05)
20	(11.62,7.90)	(457.48, 311.02)
21	(11.62,6.68)	(457.48, 262.99)
22	(11.62,5.46)	(457.48, 214.96)
23	(11.62,4.24)	(457.48, 166.93)
24	(11.62,3.02)	(457.48, 118.90)





UNLESS OTHERWISE SPECIFIED	SIGNATURES	DATE	
DIMENSIONS ARE IN MM	DRAWN:	WW1837	CYPRESS SEMICONDUCTOR Corp.
TOLERANCES ON:	CHECKED		
+/- 0.20 MM	ENGRG		
ANGLES +/-0.5 DEGREE	ISSUED		CYBT-333032/333047-02
			SIZE: REV NO: 0.1_1 DWG NO
			SCALE 5:1 THE 3RD PROJECTION SHEET: 2 OF 2